

IN THE SPECIFICATION

Please replace the paragraph starting at page 3, line 2 and ending at line 17, with the following.

--The body 18 is so configured that the above portions such as the ink supply portion 180 are unitarily molded by, for example, a resin. The ink supply portion 180 has a recess portion 182G for receiving the supporting board 20 therein. The bottom of the recess portion 182G is a surface used as a joint surface 183 on which the supporting board 20 is bonded. As shown in Figs. 6A and 6B, a part of the joint surface 183 ~~are~~ is formed of the surfaces of block pieces 26 which are formed of, for example, an aluminum alloy. The block pieces 26 are disposed in a metal mold when the body 18 is molded with the ~~metal~~ metal mold, whereby they can be covered with the resin forming the body 18. The end of the ink supply passage 184 for introducing the ink from the ink tank IT is an opening at substantially the central part of the joint surface 183.--

Please replace the paragraph starting at page 12, line 7 and ending at line 27, with the following.

--According to the above configuration, in the wiring board for feeding signals[[,]] and the like to the printing element board, a plurality of electrode wiring lines of an identical sort, for example, for feeding supply power are interconnected by the electrode wiring line in the supporting member, and hence, a part of the electrode wiring lines of the identical sort for feeding the power can be omitted in the wiring board, whereby a space for laying the other

electrode wiring lines can be relatively enlarged in the wiring board. In other words, according to the present invention, the supporting member for supporting the printing element board is utilized to be provided with ~~the~~ an electrode wiring line for making common the electrode wiring lines in the wiring board, whereby the electrode wiring lines in the wiring board can be, in effect, multilayered. Moreover, the electrode wiring lines of the wiring board are connected with the electrodes of the printing element board in a state where they are entirely covered within the wiring board itself, so that the quantity of the sealant used for connections can be lessened.--

Please replace the paragraph starting at page 14, line 21 and ending at page 15, line 17, with the following.

--The printing head of this embodiment is similar to the printing head shown in Figs. 6A, 6B and Figs. 7A, 7B, and thus in Figs. 1A - 1C, identical reference numerals are assigned to the same elements or components as shown in Figs. 6A, 6B, and 7A, 7B. This embodiment differs from the prior-art example shown in Figs. 6A and 6B, etc., in a configuration of electrical connection parts between a printing element board and a flexible board, and in a configuration of the flexible board corresponding to the configuration of electrical connection. More specifically, in a flexible board 30, electrode wiring lines 31 thereof are entirely covered within the body of the flexible board, that is, they have no exposed part. In correspondence with this arrangement, the printing element board 10 is provided with bump electrodes 40 as in the prior-art example. Then, the electrode wiring lines 31 and the bump electrodes 40 are bonded to each other by an organic resin 50 which

contains conductive particles. The flexible board 30 is formed with an opening at a portion corresponding to the printing element board 10, as shown in Fig. 1B, and most part of the printing element board 10 and a part of the supporting board 20 supporting the board 10 ~~peeped out from~~ are exposed through the opening.--

Please replace the paragraph starting at page 16, line 15 and ending at line 25, with the following.

--In this manner, ~~the~~ an electrode wiring line is laid on the supporting member so that ~~the~~ certain wiring lines of the flexible board which are connected with electrode terminals of the printing element board are made common. Thus, it is possible to vacate a region which the flexible board has heretofore required for disposing one of the electrode wiring lines 31 to be made common in the embodiment. It is consequently permitted to lay a larger number of electrode wiring lines or make the width of the electrode wiring line per se, without enlarging the width of the flexible board.--

Please replace the paragraph starting at page 17, line 17 and ending at line 25, with the following.

--As shown in these figures, only those parts of the electrode wiring line 21 which are connected with wiring lines 31 are formed as double layers. More specifically, the part of the electrode wiring line 21 ~~except~~ other than the parts thereof connected with the wiring lines 31 is buried in the supporting board 20, and only connection parts 21A thereof are exposed.

Thus, the connections between the electrode wiring line 21 and the wiring lines 31 can be facilitated.

Please replace the paragraphs starting at page 19, line 23 and ending at page 21, line 9, with the following.

--Incidentally, one form of the printing head to which the present invention is effectively applied is such that film boiling is induced in ink by utilizing thermal energy generated by an electro-thermal transducer, and that the ink is ejected by the pressure[[s]] of air bubbles ~~developed~~ generated by the boiling.

As is apparent from the above description, according to the embodiments of the present invention, in the wiring board for feeding signals[[,]] and the like to the printing element board, a plurality of electrode wiring lines of an identical sort, for example, for feeding supply power are interconnected by ~~the~~ an electrode wiring line in the supporting member, and hence, a part of the electrode wiring lines of the identical sort for feeding the power can be omitted in the wiring board, whereby a space for laying the other electrode wiring lines can be relatively enlarged in the wiring board. In other words, according to the present invention, the supporting member for supporting the printing element board is utilized to be provided with ~~the~~ an electrode wiring line for making common the electrode wiring lines in the wiring board, whereby the electrode wiring lines in the wiring board can be, in effect, multilayered. Moreover, the electrode wiring lines of the wiring board are connected with the electrodes of the printing element board in a state where they are entirely covered within the wiring board itself, so that the quantity of the sealant used for connections can be lessened.

As a result, the number or density of the electrode wiring lines of the wiring board for feeding signals, etc. to the printing element board can be increased by ~~the~~ a simple configuration.

The present invention has been described in detail with respect to preferred embodiments, and it will now be apparent from the foregoing to those skilled in the art that changes and modifications may be made without departing from the invention in its broader aspect, and it is the intention, therefore, in the ~~apparent~~ appended claims to cover all such changes and modifications as fall within the true spirit of the invention.--